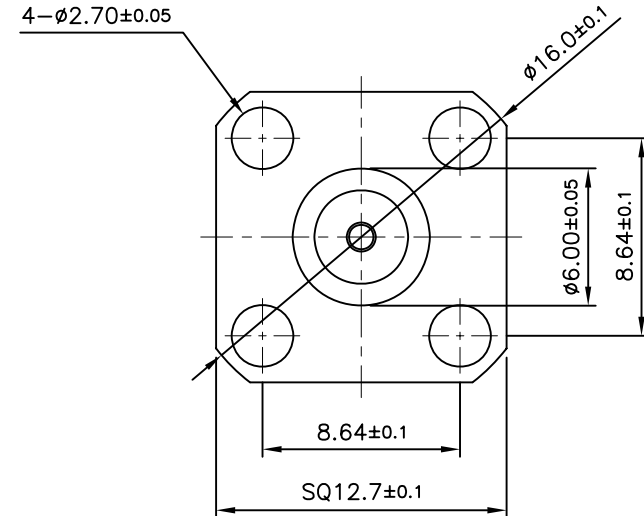
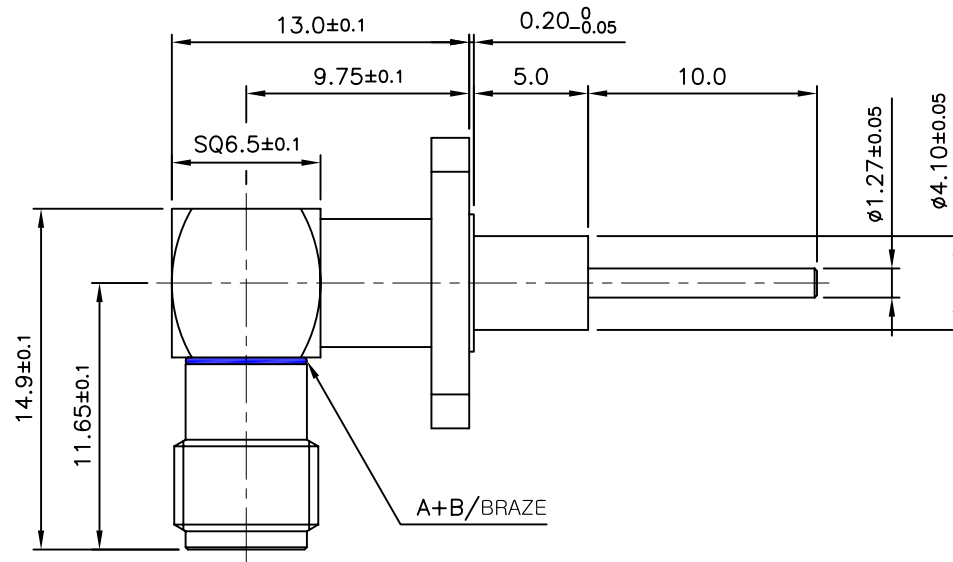


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2021.09.28.



■ 가공공차 : ISO-2768-F급 관리

6	COVER	1	MBsBD C3604BD-F	SUCO 3.0 μ m min.	DCV00038-5/2
5	INSULATOR	1	TEFLON		DIN03233-N/1
4	INSULATOR	1	TEFLON		DIN01893-N/1
3	CONTACT	1	MBsBD C3604BD-F	Silver 6.0 μ m min.	DCT04232-5/2
2	CONTACT	1	BeCu C17300	Silver 6.0 μ m min.	DCT02428-5/4
1	1-2 BODY	1	MBsBD C3604BD-F	SUCO 3.0 μ m min.	DBD02901-1/2
	1-1 BODY	1	MBsBD C3604BD-F	SUCO 3.0 μ m min.	DBD03591-1/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2021. 09. 28.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE SMA50 SOLDER END JL-4H
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	UNIT	A4 DWG NO. CN03185-7/6 REVISION I R SHEET 1 of 1
		3/1	mm	